

Organizational Chart

North America

Japan

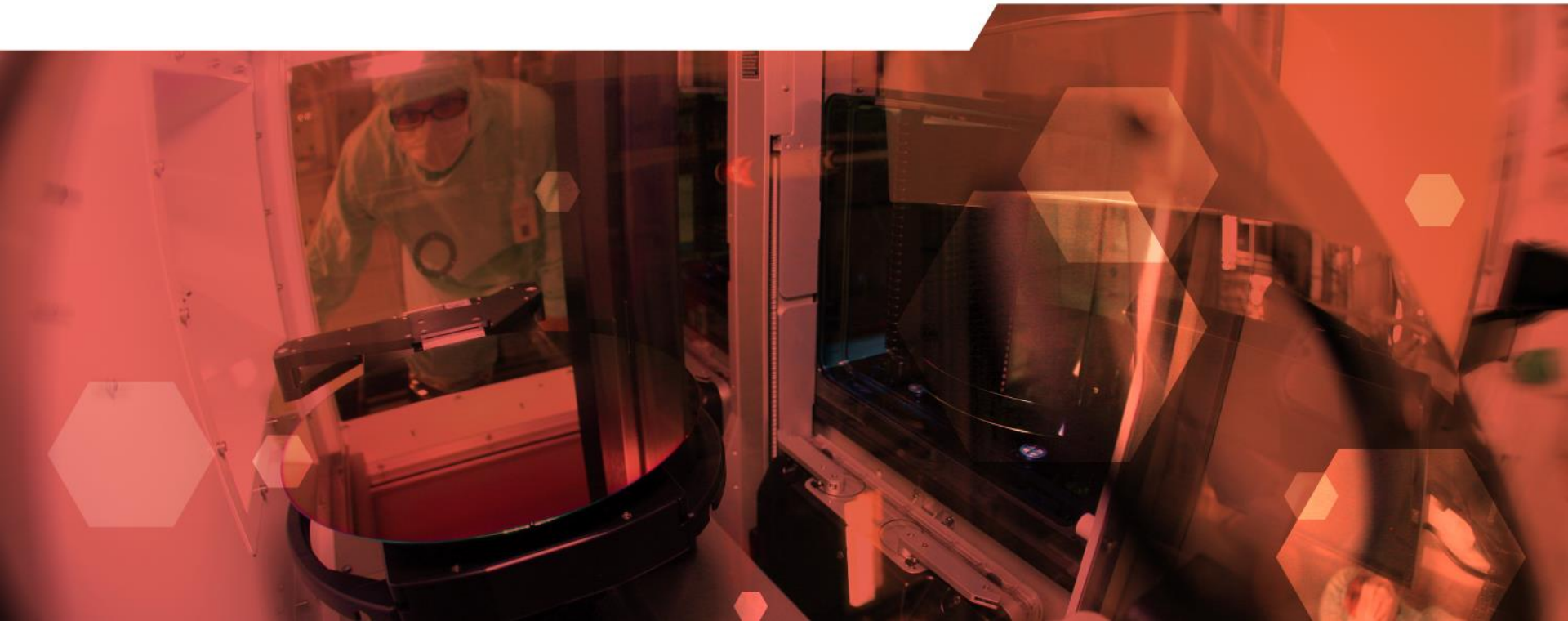
Europe

Last Updated: July 2017

Korea

Taiwan

China



Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	EH&S				TCC		TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC	CFG	TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Traceability				TCC		TCC
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED		TCC			CFG	TCC	
3DS-IC				TCC		TCC	TCC
Assembly & Packaging (Packaging**)				TCC			
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

* In NA, Micropatterning is traditionally called Microlithography

** In Japan, Assembly & Packaging is traditionally called Packaging.

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting

Vice-chair: Frank Petzold – Trustsec

**Europe Chapter of Automation
Technology Global Technical Committee**
C: Christian Hoffmann - PEER Group

**Europe Chapter of Liquid Chemicals
Global Technical Committee**
C: Jean-Marie Collard - Solvay Chemicals
C: Gordon Ferrier – Gordon F Consulting

**Europe Chapter of Physical Interfaces &
Carriers Global Technical Committee**
C: Alfred Honold - InReCon
C: Frank Petzold - Trustsec

**Europe Chapter of Compound Semiconductor
Materials Global Technical Committee**
C: Arnd Weber - SiCrystal

**Europe Chapter of Information & Control
Global Technical Committee**
C: Alfred Honold - InReCon
C: Frank Petzold - Trustsec

**Europe Chapter of PV Materials Global
Technical Committee**
C: Peter Wagner - Consultant
C: Christian Hagendorf – Fraunhofer CSP

**Europe Chapter of Gases Global
Technical Committee**
C: Jean-Marie Collard - Solvay Chemicals
C: Gordon Ferrier – Gordon F Consulting

**Europe Chapter of Metrics Global Technical
Committee**
C: Alfred Honold - InReCon
C: Lothar Pfitzner - FhG IISB

**Europe Chapter of Silicon Wafer Global
Technical Committee**
C: Werner Bergholz – International Standards
Consulting
C: Peter Wagner - Consultant
C: Fritz Passek - Siltronic

SEMI Japan RSC Organization

Co-Chair: Kenji Yamagata – Daifuku, Hidetoshi Sakura – Nu Flare Technology

Vice Chair: Supika Mashiro – TEL

Japan Chapter of 3DS-IC Global Technical Committee

C: Masahiro Tsuruya -iNEMI
C: Haruo Shimamoto - AIST

Japan Chapter of FPD Metrology Global Technical Committee

C: Ryoichi Watanabe - Japan Display
C: Akira Kawaguchi - Otsuka Electronics

Japan Chapter of PV Global Technical Committee

C: Kazuhiko Kashima – Tokyo Institute of Technology
C: Masaaki Yamamichi – RTS Corporation

Special Groups

Reporting to the JRSC

Japan Chapter of Automation Technology Global Technical Committee

C: Terry Asakawa -Consultant
C: Teruaki Ito - Mitsubishi Electric

Japan Chapter of Information & Control Global Technical Committee

C: Takayuki Nishimura - SCREEN Semiconductor Solutions
C: Mitsuhiro Matsuda - Hitachi Kokusai Electric

Japan Chapter of PV Materials Global Technical Committee

C: Takashi Ishihara - Mitsubishi Electric
C: Kazuhiko Kashima – Tokyo Institute of Technology
C: Tetsuo Fukuda - AIST

Standardization Process Improvement (SPI)

L: Supika Mahiro -TEL

Japan Chapter of Compound Semiconductor Materials Global Technical Committee

C: Masayoshi Obara - Shin-Etsu Handotai

Japan Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita - Toshiba
C: Hiroyuki Araki - SCREEN Semiconductor Solutions

Japan Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Tsuyoshi Nagashima - Miraial
C: Kenji Yamagata – DAIFUKU
C: Noriyoshi Toyoda – Hirata Corporation

Japan Chapter of Environmental Health & Safety Global Technical Committee

C: Supika Mashiro - TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford - Hatsuta Seisakusho

Japan Chapter of Metrics Global Technical Committee

C: Toshio Murakami – Murakami Corporation

Japan Chapter of Silicon Wafer Global Technical Committee

C: Naoyuki Kawai - Self
C: Tetsuya Nakai - SUMCO

Japan Chapter of Gases & Facilities Technical Committee

C: Hiromichi Enami - Hitachi High-Technologies
C: Isao Suzuki - MKS Japan

Japan Chapter of Assembly & Packaging Global Technical Committee

C: Kazunori Kato - AiT
C: Masahiro Tsuruya - iNEMI

Japan Chapter of Traceability Global Technical Committee

C: Yoichi Iga - JSA
C: Hirokazu Tsunobuchi - Keyence

Japan Chapter of FPD Materials & Components Global Technical Committee

C: Tadahiro Furukawa - Yamagata University
C: Yoshihiko Shibahara - FUJIFILM

SEMI North America (NA) RSC Organization - NA Locale

Co-Chairs: Steve Lewis – BW Design Group & Chris Evanston – Salus Engineering

Vice-Chairs: Brian Rubow – Cimatrix

NA Chapter of 3DS-IC Global Technical Committee

C: Richard Allen - NIST
C: Sesh Ramaswami - Applied Materials
C: Chris Moore – Frontier Semiconductor

NA Chapter of Gases Global Technical Committee

C: Mohamed Saleem – Brooks
Instrument

NA Chapter of Metrics Global Technical Committee

C: David Bouldin - Fab Consulting
C: Mark Frankfurth – Cymer
C: Vladimir Kraz – BestESD

NA Chapter of Silicon Wafer Global Technical Committee

C: Dinesh Gupta - STA
C: Noel Poduje - SMS
VC: Mike Goldstein

NA Chapter of Automated Test Equipment Global Technical Committee

C: Ajay Khoche - Khoche Consulting

NA Chapter of HB-LED Global Technical Committee

C: Iain Black - Philips
C: Mike Feng - Silian
C: Chris Moore – Frontier Semiconductor
C: Andrew Kim - InnovationforX

NA Chapter of Microlithography Global Technical Committee

C: Wes Erck - Wes Erck & Associates
C: Bryan Barnes - NIST

NA Chapter of Traceability Global Technical Committee

C: Win Baylies - BayTech-Resor
C: Yaw Obeng - NIST

NA Chapter of Compound Semiconductor Materials Global Technical Committee

C: Russ Kremer - Freiburger Compound Materials
C: James Oliver - Northrop Grumman

NA Chapter of Information & Control Global Technical Committee

C: Jack Ghiselli - Ghiselli Consulting
C: Brian Rubow – Cimatrix
C: James Moyne – AMAT/ University of
Michigan

NA Chapter of Photovoltaic Global Technical Committee

C: Win Baylies - BayTech-Resor
C: James Moyne – AMAT / University of
Michigan

NA RSC Technical Architect Board

C: James Moyne – AMAT /
University of Michigan
C: Yaw Obeng - NIST

NA Chapter of Environmental Health & Safety Global Technical Committee

C: Chris Evanston - Salus Engineering
C: Sean Larsen - Lam Research
C: Bert Planting - ASML

NA Chapter of Liquid Chemicals Global Technical Committee

C: Frank Flowers – PeroxyChem
C: Don Hadder – Intel

NA Chapter of PV Materials Global Technical Committee

C: Hugh Gotts - Air Liquide

NA Chapter of Facilities Global Technical Committee

C: Steve Lewis – BW Design Group

NA Chapter of MEMS/NEMS Global Technical Committee

C: Win Baylies - BayTech-Resor
C: Steve Martell - Sonoscan

NA Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Matt Fuller - Entegris
C: Melvin Jung - Intel

SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group & Chris Evanston – Salus Engineering

Vice-Chairs: Brian Rubow – Cimatrix

**China Chapter of PV Global
Technical Committee**

C: Guangchun Zhang -
CanadianSolar
C: Jun Liu - China Electronics
Standardization Institute

**China Chapter of PV Materials
Global Technical Committee**

C: Guangchun Zhang -
CanadianSolar
C: Jun Liu - China Electronics
Standardization Institute

**China Chapter of HB-LED
Global Technical Committee**

C: Yong Ji - Guizhou Haotian
Optoelectronics Technology
C: Weizhi Cai - San'an
Optoelectronic

SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group & Chris Evanston – Salus Engineering

Vice-Chairs: Brian Rubow – Cimatrix

Korea HB-LED CFG

L: HyeongSoo Park - SEMES
L: Jong Hyeob Baek - KOPTI

Korea Chapter of FPD Materials & Components Technical Committee

C: JongSeo Lee - Samsung Display
C: Il-Ho (William) Kim - Light Measurement Solution

Korea Chapter of Global Facilities Technical Committee

C: Kwang Sun Kim - KUT

Korea Chapter of FPD Metrology Global Technical Committee

C: JongSeo Lee - Samsung Display
C: Il-Ho (William) Kim - Light Measurement Solution

Korea Chapter of Information & Control Global Technical Committee

C: Hyungsu Kim - Doople
C: Chul Hong Ahn - SK hynix
C: Gun Woo Lee - Lam Research

SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group & Chris Evanston – Salus Engineering

Vice-Chairs: Brian Rubow – Cimatrix

**Taiwan Chapter of 3DS-IC
Global Technical Committee**

C: Wendy Chen - King Yuan
Electronics
C: Chien-Chung Lin – ITRI
C: Roger Hwang - ASE

**Taiwan Chapter of EHS Global
Technical Committee**

C: Shuh-Woei Yu - SAHTECH
C: Fang-Ming Hsu - TSMC

**Taiwan Chapter of Information and
Control Global Technical Committee**

C: Robert Chien - TSMC

**Taiwan TC Chapter of Automation
Technology Global Technical Committee**

C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI
C: Gwo-Sheng – ITRI/CMS
C: C.S. Wu – MIRDC

**Taiwan Chapter of Flat Panel Display
Global Technical Committee**

C: Mike Yao - CMS/ITRI
C: Jia-Ming Liu - TDMDA

**Taiwan Chapter of Photovoltaic
Global Technical Committee**

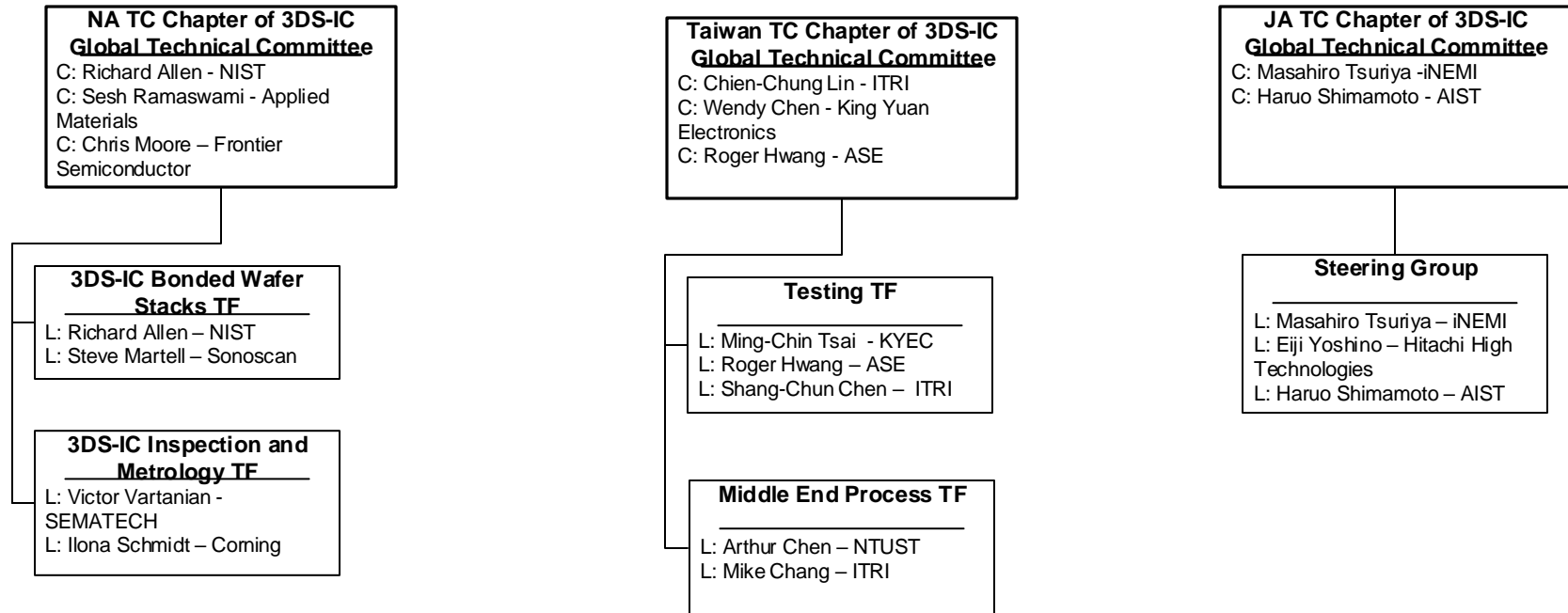
C : B. N. Chuang - CMS/ITRI
C : J.S. Chen - TeraSolar
C : Ray Sung - UL Taiwan

ISC Taiwan Advisor

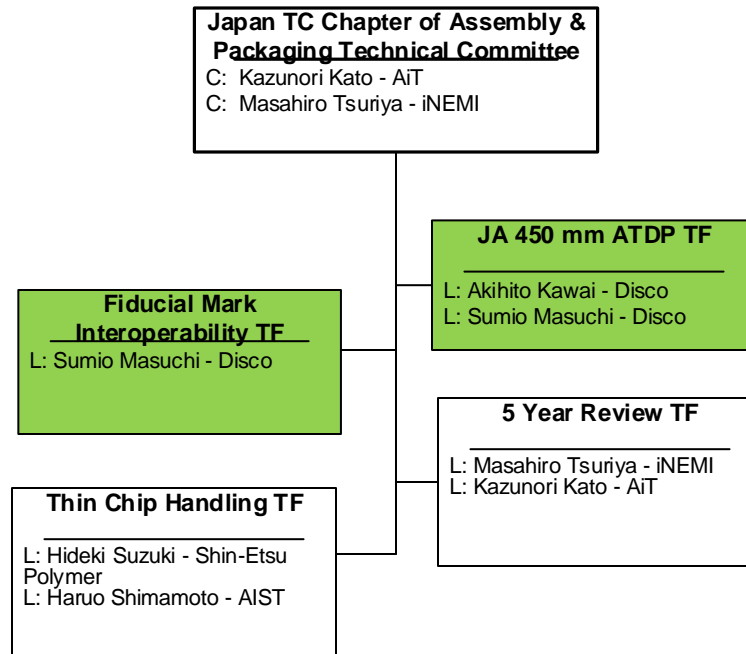
Tzeng-Yow Lin - CMS/ITRI

Organization of Each TC Chapter

3DS-IC Global Technical Committee



Assembly & Packaging Global Technical Committee



= Global Task Force

Automation Technology Global Technical Committee

**Europe TC Chapter of Automation
Technology Global Technical Committee**
C: Christian Hoffmann - PEER Group

**Global Equipment Interface
Specification (EIS) TF**
L: Carsten Born - VITRONIC GmbH

PV Wafer Traceability TF
L: TBD

**Japan TC Chapter of Automation
Technology Global Technical Committee**
C: Teruaki Ito - Mitsubishi Electric
C: Terry Asakawa - Consultant

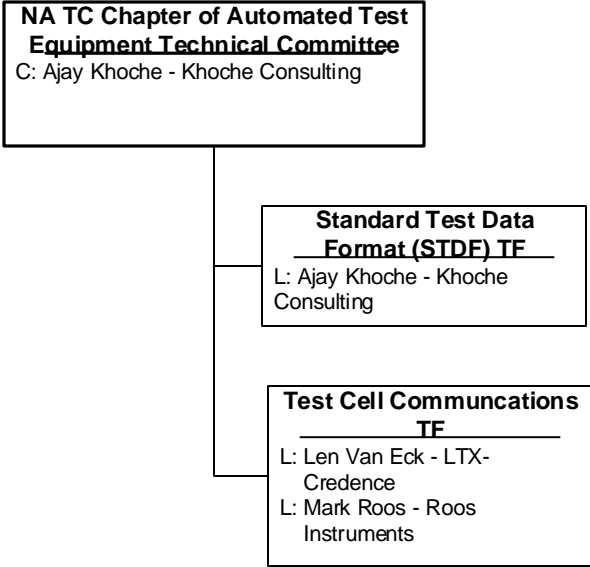
**Global Equipment Interface
Specification (EIS) TF**
L: Katsuyoshi Takahashi - Mitsubishi
Electric

**Taiwan TC Chapter of Automation
Technology Global Technical Committee**
C: K.C. Chou - ASE
C: Jen-Hui Tsai - ITRI
C: Gwo-Sheng - ITRI/CMS
C: C.S. Wu - MIRDC

PCBECI TF
L: Kuang-Fu Chang - ASE
L: Chi-Pin Chen - ITRI
L: Chi-Yuan Chang - Symtek



Automated Test Equipment Global Technical Committee



Compound Semiconductor Materials (CSM) Global Technical Committee

**Europe TC Chapter of CSM
Global Technical Committee**
C: Arnd Weber - SiCrystal

**Contactless Resistivity
and Mobility Mapping TF**
L: Wolfgang Jantz - Semimap

SiC TF
L: Arnd Weber - SiCrystal

M54 Revision TF
L: Ulrich Kretzer – Freiberger
Compound Materials GmbH

**Japan TC Chapter of CSM
Global Technical Committee**
C: Masayoshi Obara - Shin-Etsu
Handotai
C: TBD

International SiC TF
L: Taizo Hoshino - Nippon Steel
& Sumikin Materials

Sapphire Substrate TF
L: TBD

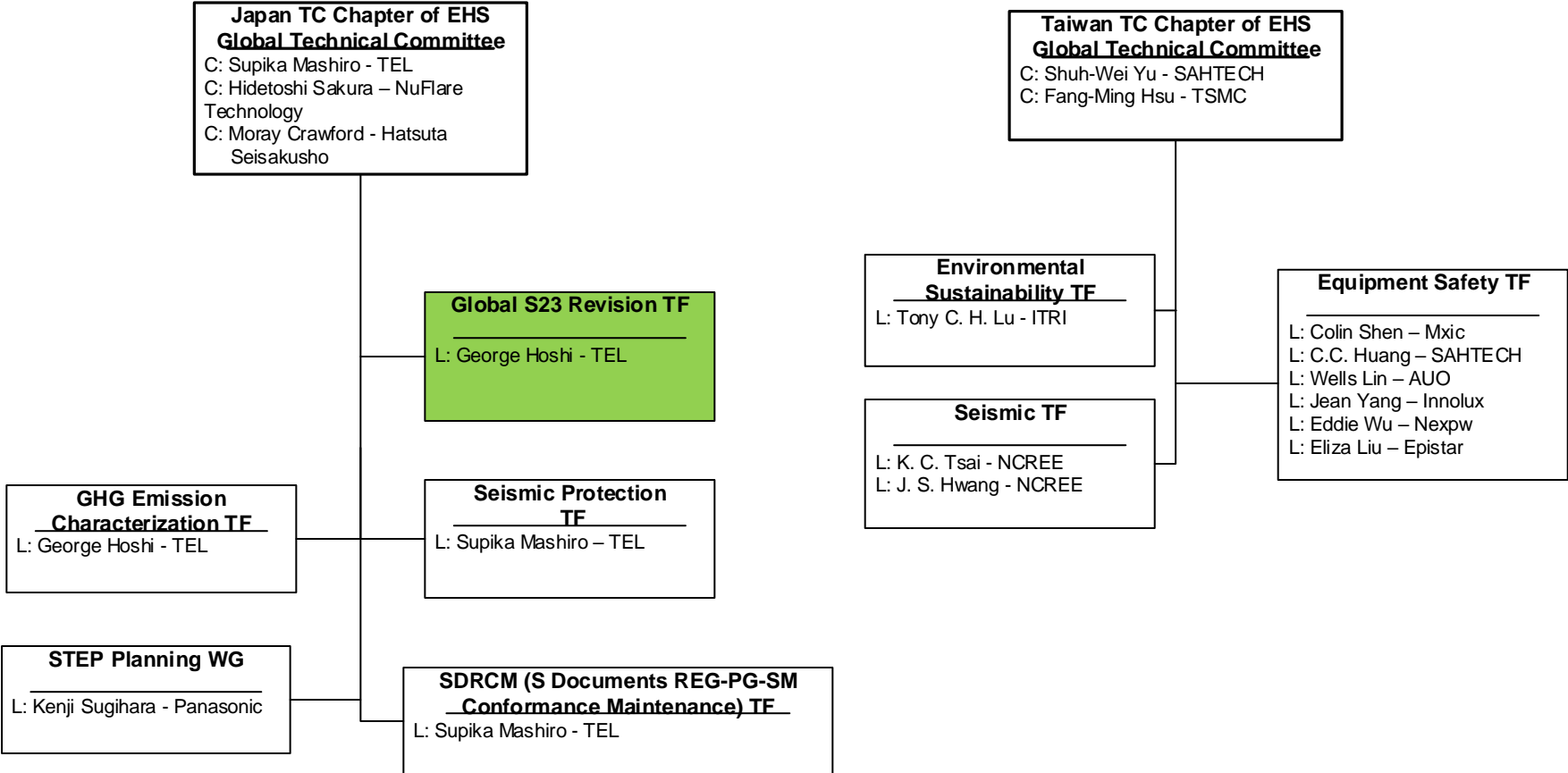
5 Year Review TF
L: TBD


**Global 200 mm GaAs
Wafer Specification TF**
L: TBD

**NA TC Chapter of CSM Global
Technical Committee**
C: Russ Kremer - Freiberger
Compound Materials
C: James Oliver - Northrop
Grumman

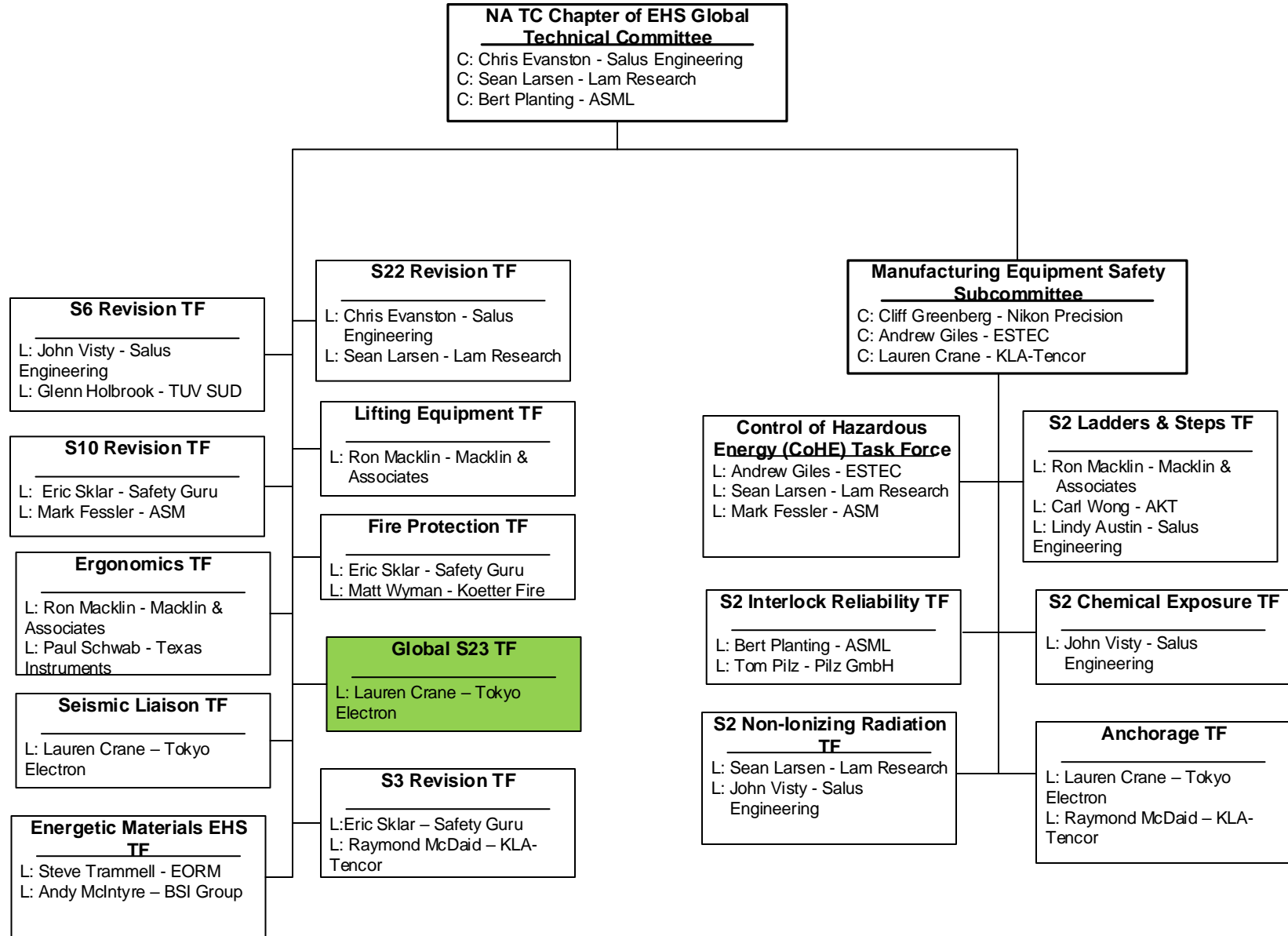
Silicon Carbide TF
L: TBD

Environmental, Health & Safety (EHS) Global Technical Committee



 = Global Task Force

Environmental, Health & Safety Global Technical Committee



Facilities Global Technical Committee

**Japan TC Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami - Hitachi High
Technologies
C: Isao Suzuki - MKS Japan

F1 Revision TF
L: Shuji Moriya - TEL
Yamanashi
L: Yoshifumi Machii - Fujikin

**Korea TC Chapter of Facilities
Global Technical Committee**
C: Kwang Sun Kim - KUT

Equipment Cleanness TF
L: TBD

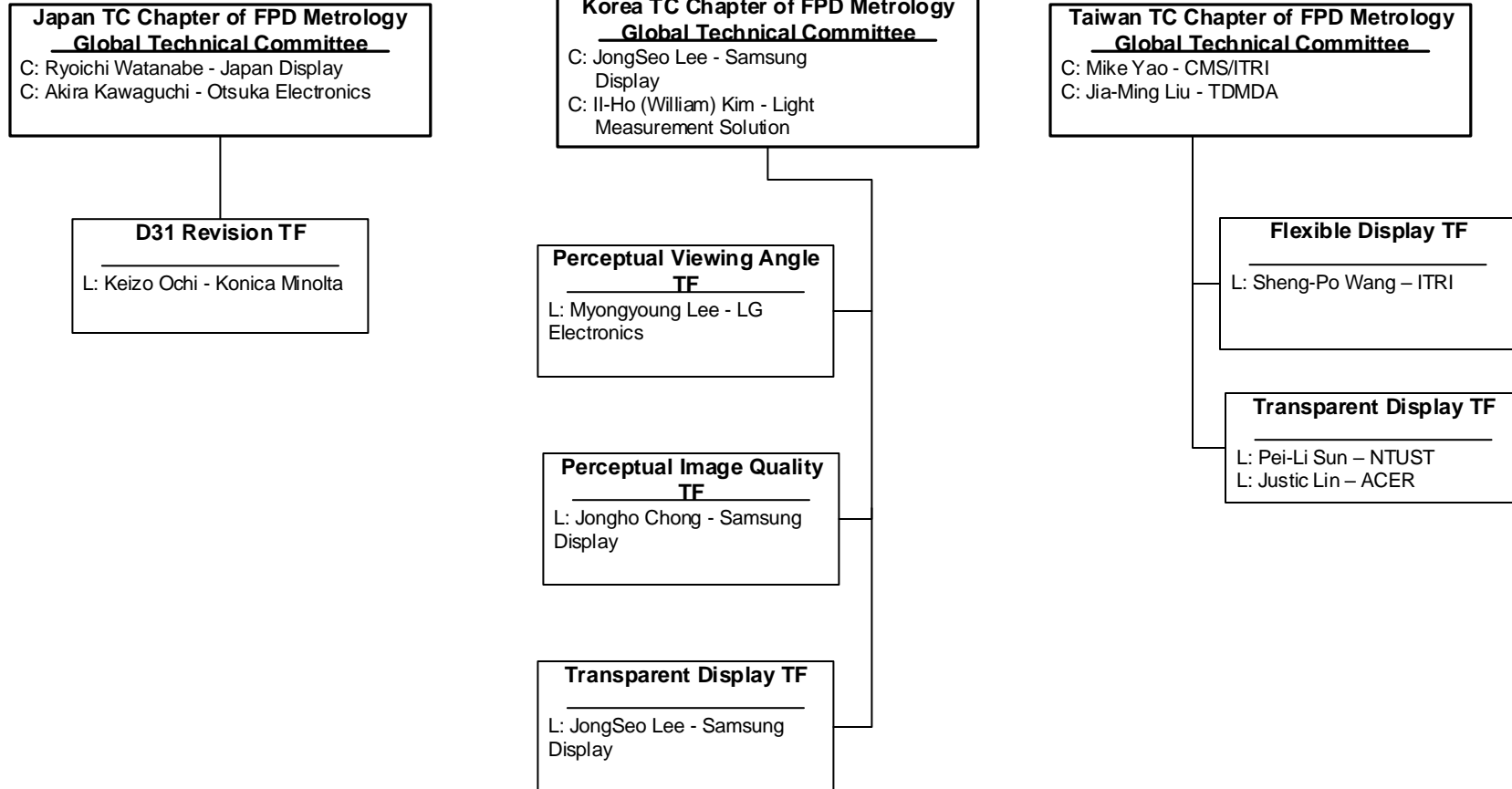
**NA TC Chapter of Facilities
Global Technical Committee**
C: Steve Lewis – BW Design Group

F51 Revision TF
L: Dalia Vernikovsky - Applied
Seals North America

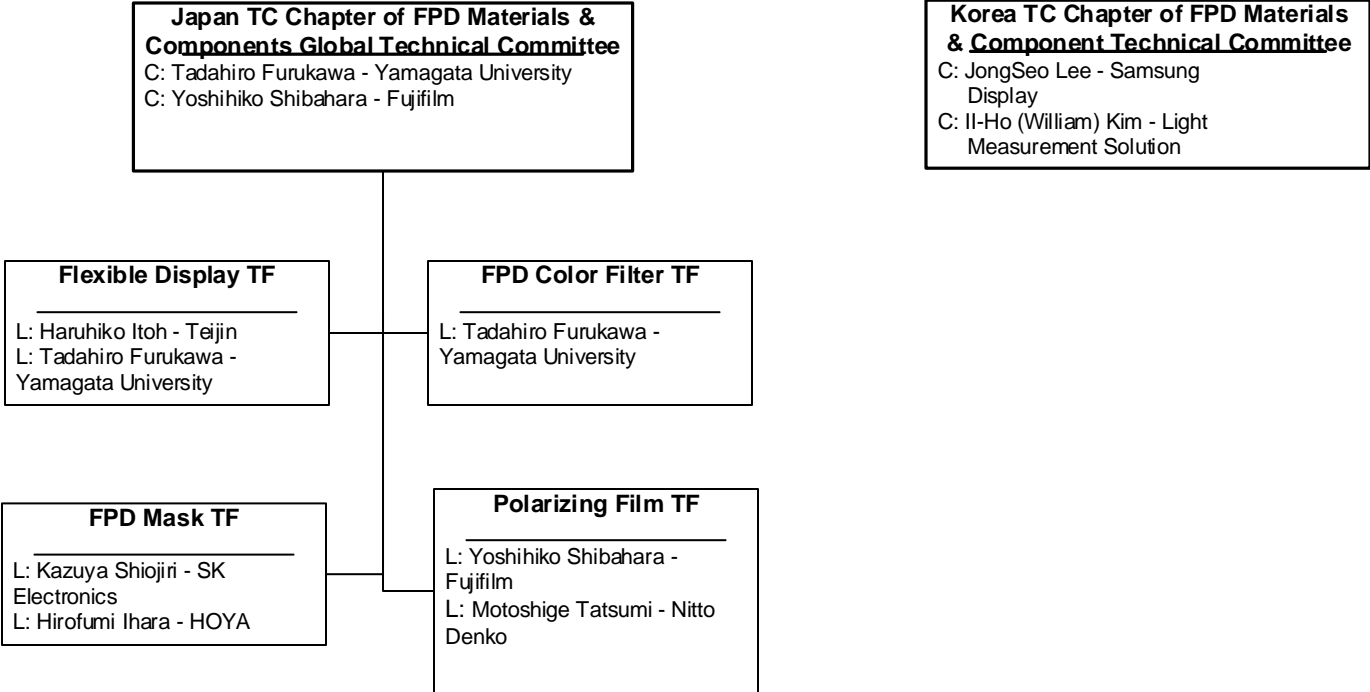
**Building Information Modeling (BIM) for
Semiconductor Capital Equipment TF**
L: Ben Bruce - Applied Materials

Power Grid Harmonics TF
L: Alex McEachern – Power
Standards Lab

FPD Metrology Global Technical Committee



FPD Materials & Components Global Technical Committee



Gases Global Technical Committee

**Europe TC Chapter of Gases
Global Technical Committee**
 C: Jean-Marie Collard - Solvay
 Chemicals
 C: Gordon Ferrier - Gordon F
 Consulting

**Permeation Tubes for Trace
Moisture Calibration TF**
 L: Jean-Marie Collard - Solvay
 Chemicals
 L: Jim Mc Kinley - KIN-TEK

Cleaning Gases TF
 L: Jean-Marie Collard - Solvay
 Chemicals

**Japan TC Chapter of Gases
Global Technical Committee**
 C: Hiromichi Enami - Hitachi High
 Technologies
 C: Isao Suzuki - MKS Japan

Gas Panel Test Method TF
 L: Yoshifumi Machii - Fujikin
 L: Shuji Moriya - TEL
 Yamanashi

5 Year Review TF
 L: Yoshifumi Machii - Fujikin

Live Gas Flow Rate TF
 L: Moriya Shuji - TEL Yamanashi
 L: Shimizu Tetsuo - Horiba STEC
 L: Ishihara Seiji - Flow Techno
 Service

**NA TC Chapter of Gases
Global Technical Committee**
 C: Mohamed Saleem – Brooks
 Instrument

Filters & Purifiers TF
 L: Mohamed Saleem – Brooks
 Instrument
 L: Yanli Joyce Chen – UCT

Heater Jacket TF
 L: David Colquhoun - BriskHeat

Mass Flow Controller TF
 L: Mohamed Saleem – Brooks
 Instrument
 L: Erica Kitano – Fujikin

Gases Specification TF
 L: Mohamed Saleem – Brooks
 Instrument
 L: Thomas Fritz – WIKA

**Materials of Construction
Gas Delivery Systems TF**
 L: Bill Kiikvee - AP TECH

**Pressure Measurement TF
(Inactive)**
 L: Yanli Joyce Chen - UCT
 L: Jeff Christian - WIKA

**Surface Mount Sandwich
Component Dimensions TF
(Inactive)**
 L: Matt Milburn - UCT

HB-LED Global Technical Committee

**China TC Chapter of HB-LED
Global Technical Committee**
 C: Yong Ji - Guizhou Haotian
 Optoelectronics Technology
 C: Weizhi Cai - San'an
 Optoelectronic

Korea HB-LED CFG
 L: HyeongSoo Park - SEMES
 L: Jong Hyeob Baek - KOPTI

**NA TC Chapter of HB-LED
Global Technical Committee**
 C: Iain Black - Philips
 C: Mike Feng - Silian
 C: Chris Moore - Frontier
 Semiconductor
 C: Andrew Kim - InnovationforX

- Single Crystal Sapphire TF**
 L: Yong Ji - Guizhou Haotian
 Optoelectronics Technology
 L: Xinhong Yang - AURORA
- Sapphire Single Crystal Ingot TF**
 L: Hongbo Zuo - AURORA
- GaN based LED Epitaxial Wafer TF**
 L: Jiangbo Wang - HC SemiTek
- Sapphire Single Crystal Orientation TF**
 L: Songbin Zhao - DDXDF
- Patterned Sapphire Substrate TF**
 L: Jianzhe Liu - ECBO

Patterned Sapphire Substrate (PSS) TF
 L: Win Bayles - BayTech-Resor

HB-LED Wafer TF
 L: Win Bayles - BayTech-Resor

HB-LED Equipment Communication Interfaces TF (Inactive)
 L: Brian Rubow - Cimatrix

HB-LED Assembly TF
 L: Paul Reid - Kulicke & Soffa

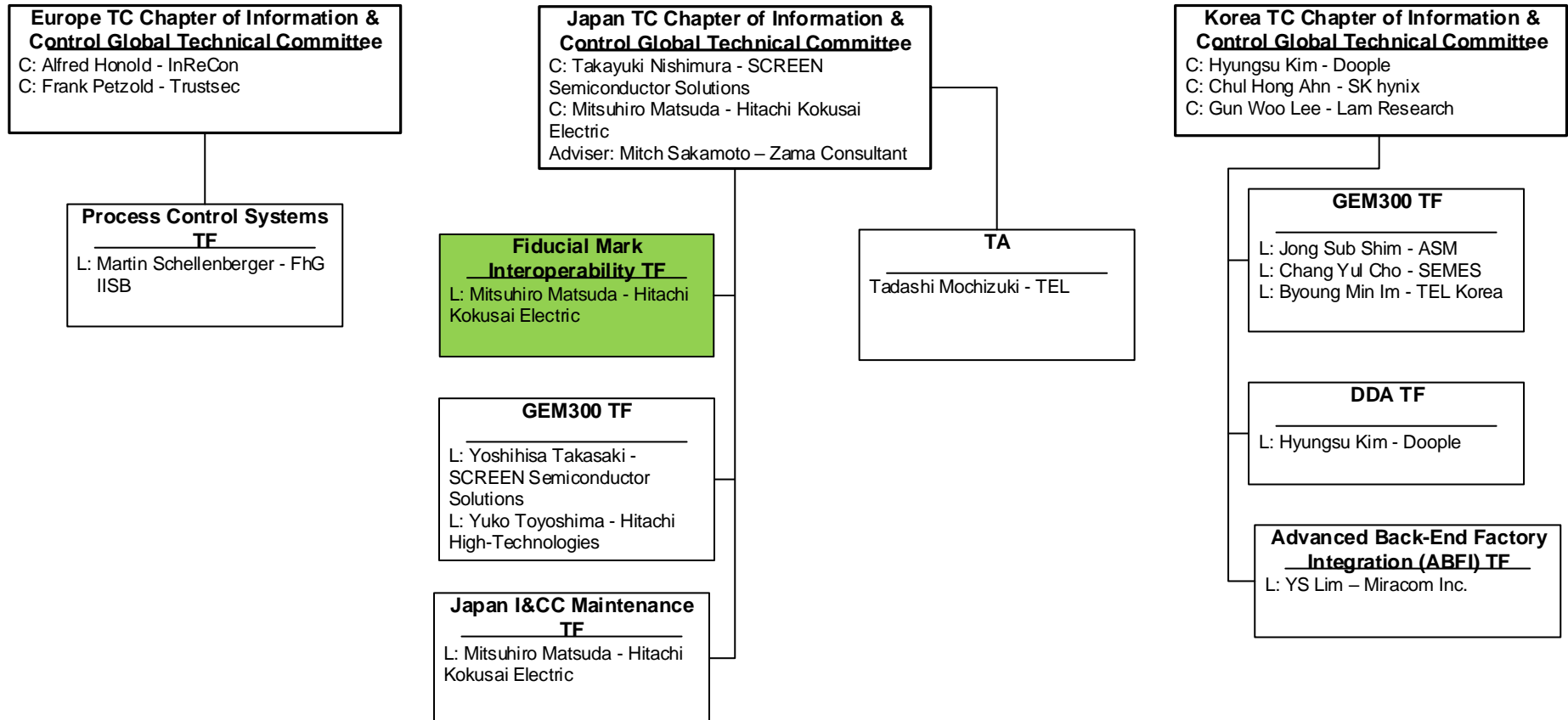
HB-LED Impurities and Defects in Sapphire Wafers TF (Inactive)
 L: Luke Glinski - GT Advanced Technologies

HB-LED Equipment Automation Interfaces TF (Inactive)
 L: Daniel Babbs - Brooks Automation
 L: Jeff Felipe - Entegris

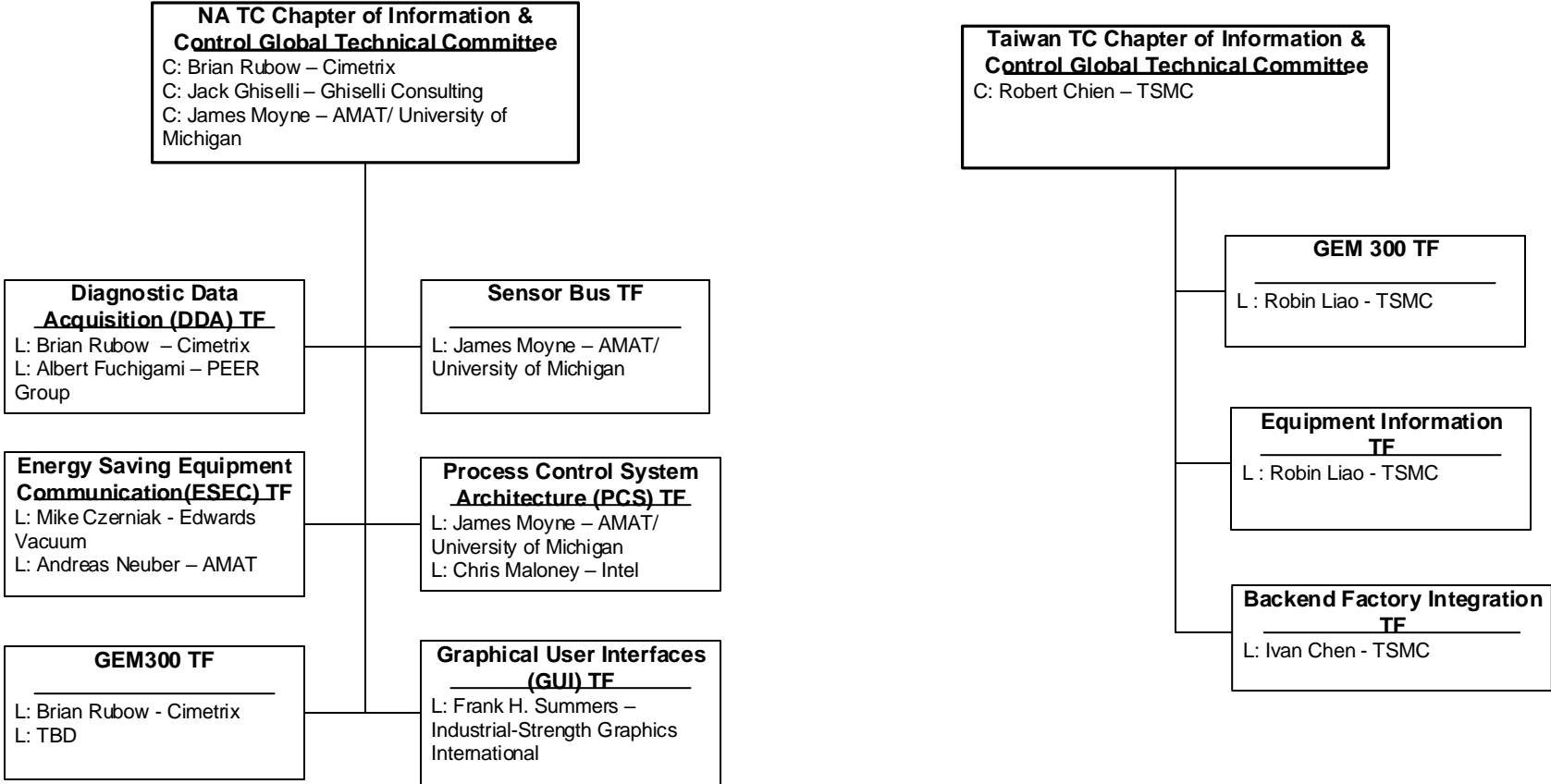
HB-LED Source Materials TF (Korea)
 L: Paul Ahn - Veeco
 L: H.B. Joo - Aixtron
 L: Sungjin Jun - LG Innotek
 L: Deok-gil - Samsung Electronics

Test Methods TF (Inactive)
 L: Peter Wagner - Self

Information & Control Global Technical Committee



Information & Control Global Technical Committee



Liquid Chemicals Global Technical Committee

Europe TC Chapter of Liquid Chemicals Global Technical Committee

C: Jean-Marie Collard - Solvay Chemicals
C: Gordon Ferrier - Tiger Optics

Precursor Specifications TF

L: Paul Williams - SAFC Hitech

Solvents in Advanced Processes TF

L: TBD

Japan TC Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita – Toshiba Memory
C: Hiroyuki Araki - SCREEN Semiconductor Solutions

Liquid Filter TF

L: Takuya Nagafuchi - Nihon Entegris
L: Takehito Mizuno - Nihon Pall

Liquid-Borne Particle Counter TF

L: Kaoru Kondo - RION
L: Kazutoshi Kato - PMS

Diaphragm Valve TF

L: Shigeru Ohsugi - CKD
L: Kimihito Sasao - Advance Electric

Welding Fitting TF

L: Kimihito Sasao - Advance Electric
L: Takashi Hasegawa - KITZ SCT

Ultrapure Liquid Evaluation Study Group

L: Kaoru Kondo - Rion
L: Hiroshi Sugawara - Organo

Korea Gas & Liquids Chemicals CFG

L: TBD

NA TC Chapter of Liquid Chemicals Global Technical Committee

C: Frank Flowers - PeroxyChem
C: Don Hadder – Intel

Chemical Analytical Methods TF

L: Frank Flowers – PeroxyChem
L: Don Hadder – Intel

High Purity Liquid Assemblies & Systems TF

L: Koh Murai - Mega Fluid Systems

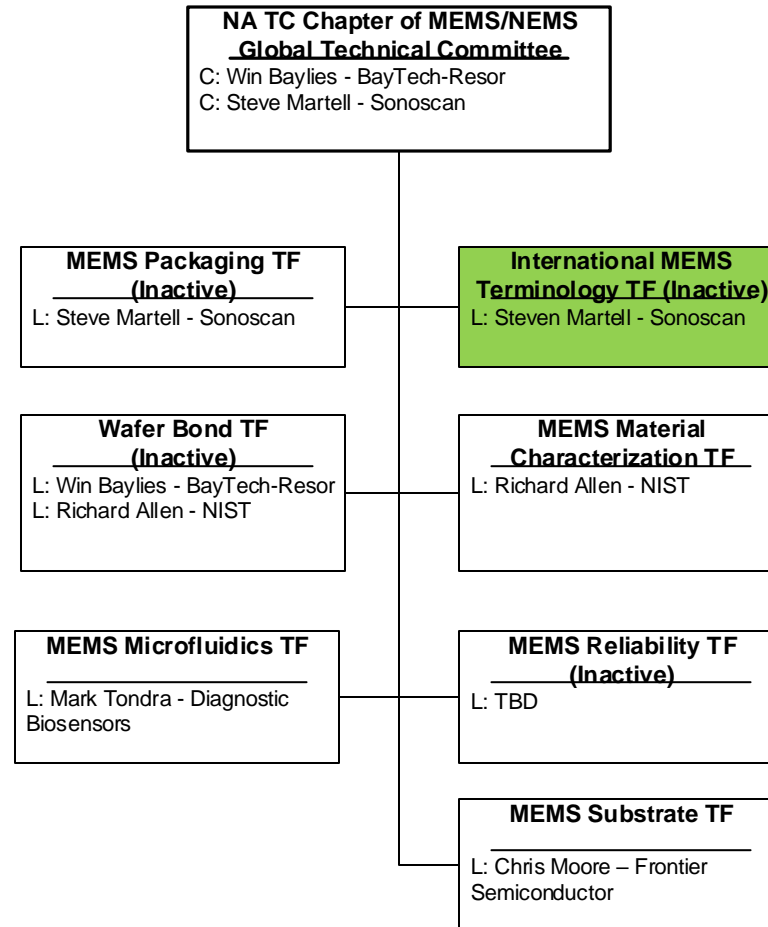
High Purity Polymer Materials & Components TF

L: Bob McIntosh – GF Piping

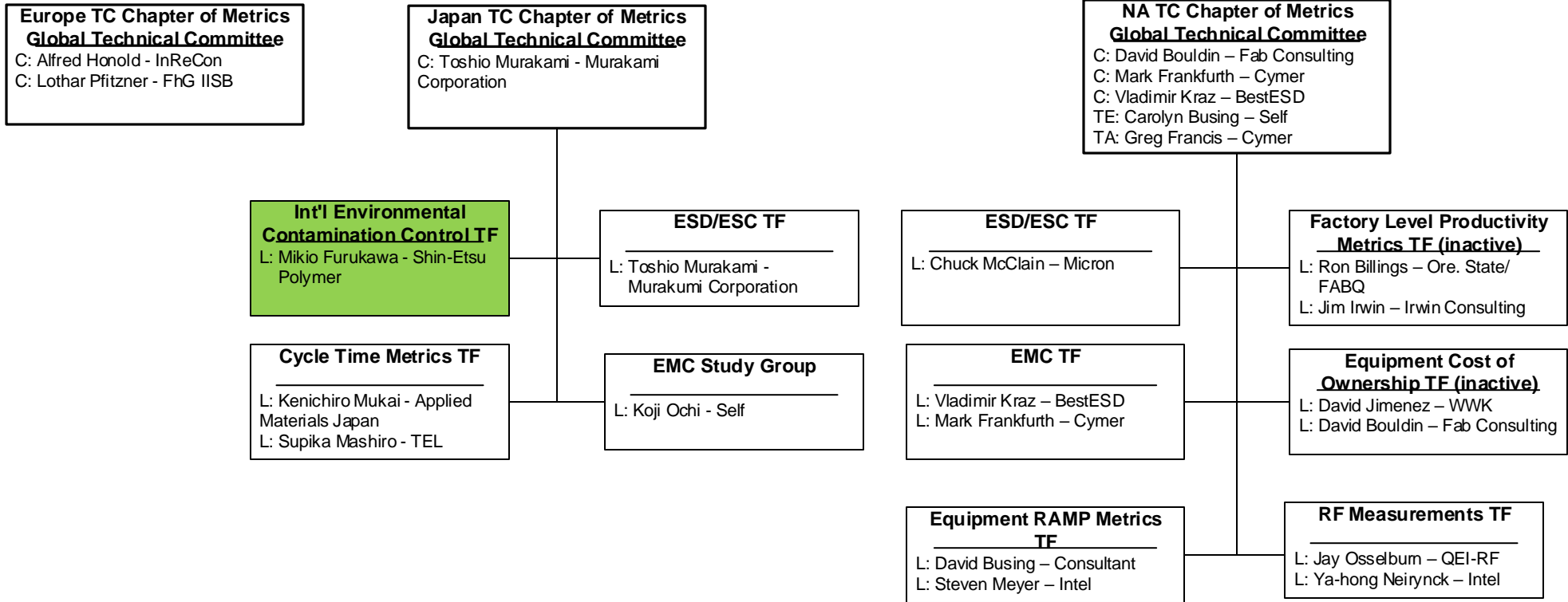
Ultra Pure Water (UPW) TF

L: Slava Libman - Air Liquide
L: Bob McIntosh – GF Piping

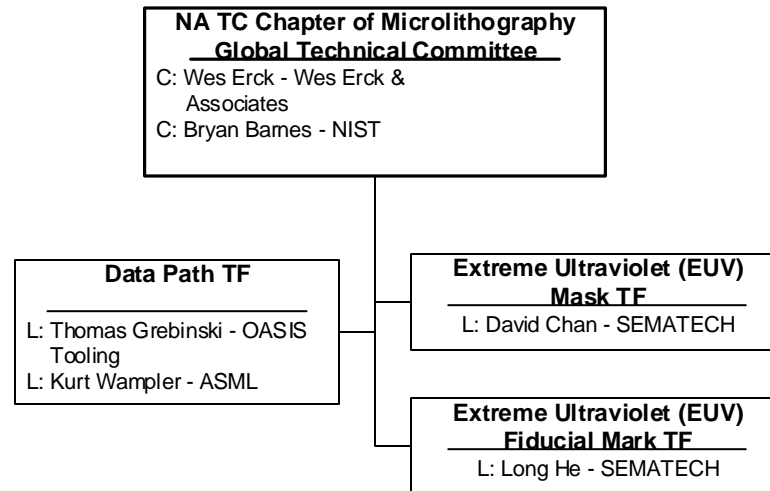
MEMS/NEMS Global Technical Committee



Metrics Global Technical Committee



Micropatterning Global Technical Committee



Photovoltaic Global Technical Committee

China TC Chapter of PV Global Technical Committee
 C: Guangchun Zhang - CanadianSolar
 C: Jun Liu - China Electronics Standardization Institute

Japan TC Chapter of Global PV Technical Committee
 C: Kazuhiko Kashima - Tokyo Institute of Technology
 C: Masaaki Yamamichi - RTS Corporation

NA TC Chapter of Global PV Technical Committee
 C: Win Baylies - BayTech-Resor
 C: James Moyné - AMAT / University of Michigan

Taiwan TC Chapter of PV Global Technical Committee
 C: B. N. Chuang - CMS/ITRI
 C: J.S. Chen - TeraSolar
 C: Ray Sung - UL Taiwan

Crystalline Silicon Solar Cell TF
 L: Dengyuan Song - YingLi Energy
 L: Rulong Chen - Suntech
 L: Xianwu Cai - 48th Institute

Thin Film PV Module TF
 L: Yaohua Mai - Hebei University
 L: Xinwei Niu - JA Solar
 L: Jian Ding - Hanergy

PV Diffusion Furnace Test Methods TF
 L: Liangyu Liu - CETC-48
 L: Xianwu Cai - CETC-48
 L: Li Hong - SevenStar

Multi-Wire Saws TF
 L: Jingying Jia - NERCPVE
 L: Xianwu Cai - CETC-48
 L: Zhixin Li - LCT
 L: Wenli Lv - CETC-48

PV Module TF
 L: Wei Zhou - Trina Solar
 L: Liang Luo - Hunan Red Solar
 L: Zhen Zhang - Hohai University
 L: Jingbing Zhu - Sunman

Testing Equipment TF
 L: Hui Long - CETC-48

PV Package Performance TF
 L: C.C.Lin - PV Guider
 L: T.C. Wu - CMS/ITRI
 L: Ivan Chou - Eterbright Solar
 L: K.T.Lee - King Design

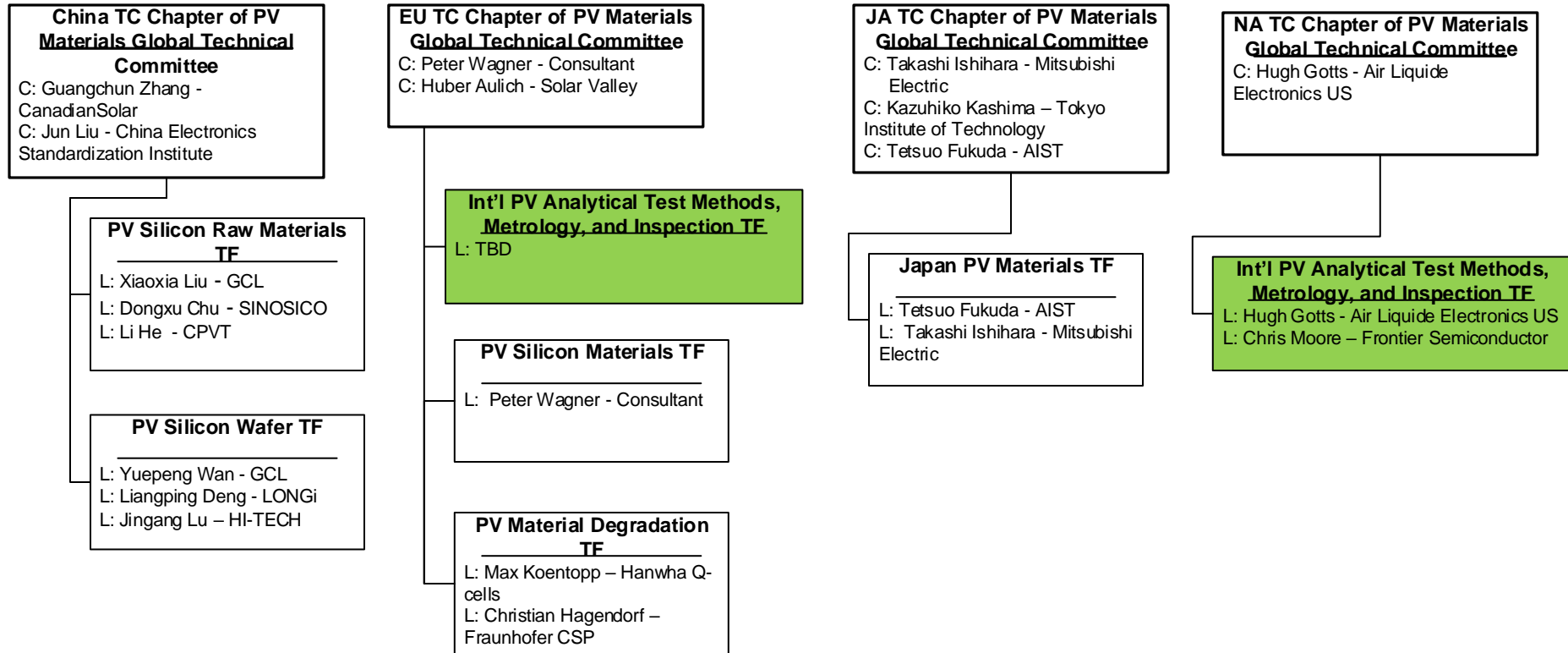
PV Reliability Test Method TF
 L: H.S. Wu - CMS/ITRI

CIGS Solar Cell TF
 L: D. R. Huang - NDHU
 L: T.C. Wu - CMS/ITRI
 L: Jason Shin - King Design
 L: H.S. Koo - MUST
 L: William Hou - Sunshine PV

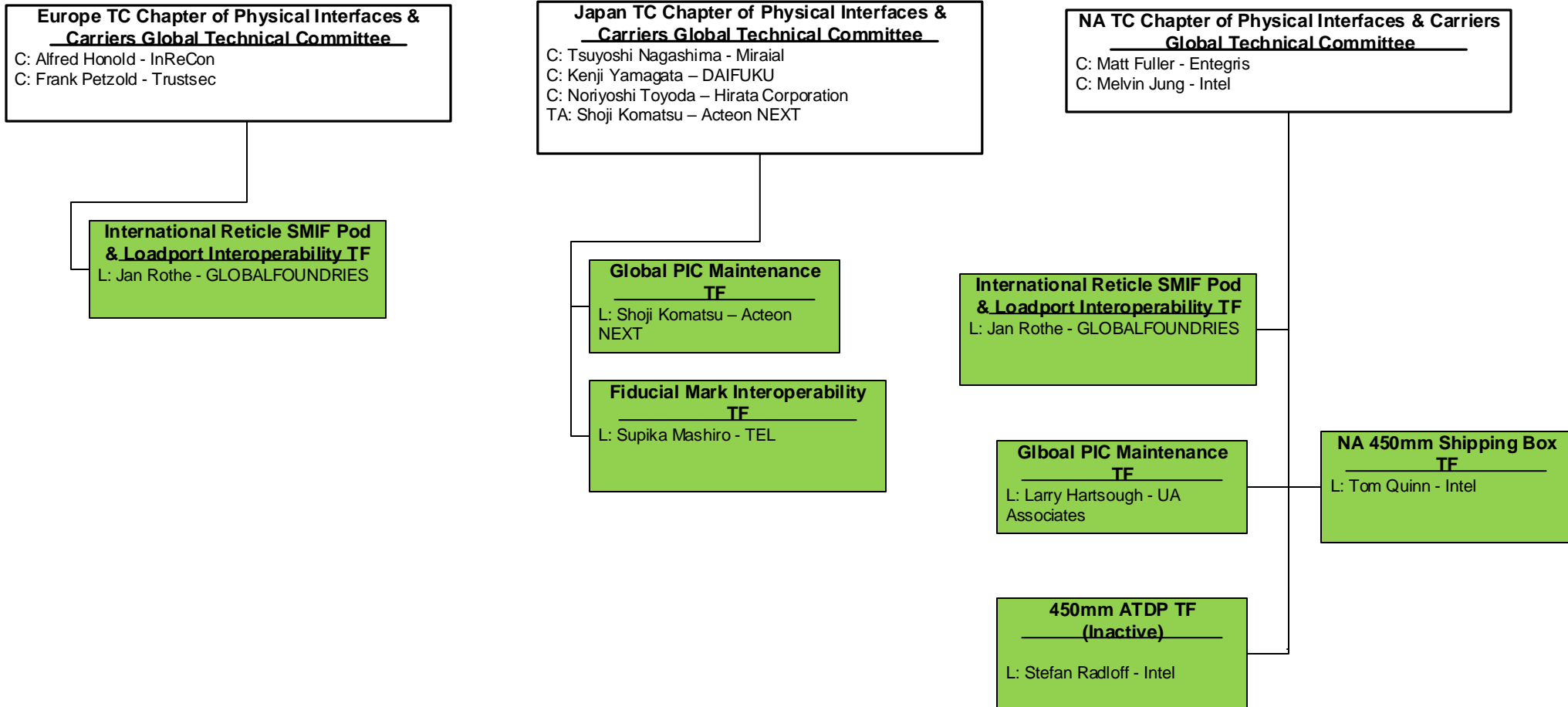
Building Integrated Photovoltaic (BIPV) TF
 L: C.C. Lin - PV Guider
 L: D. R. Huang - NDHU
 L: T.C. Wu - CMS/ITRI
 L: Ivan Chou - Eterbright Solar
 L: K.T. Lee - King Design
 L: K.H. Ke - Grain System

Organic, Dye Sensitized & Perovskite Solar Cell TF
 L: D. R. Huang - NDHU
 L: T.C. Wu - CMS/ITRI
 L: Kevin Chou - Everlight
 L: Jason Shin - King Design
 L: Y. M. Yang - NCKU
 L: H.S. Koo - MUST
 L: C. G. Wu - NCU
 L: S. H. Tu - TDP
 L: C. C. Tsao - INER

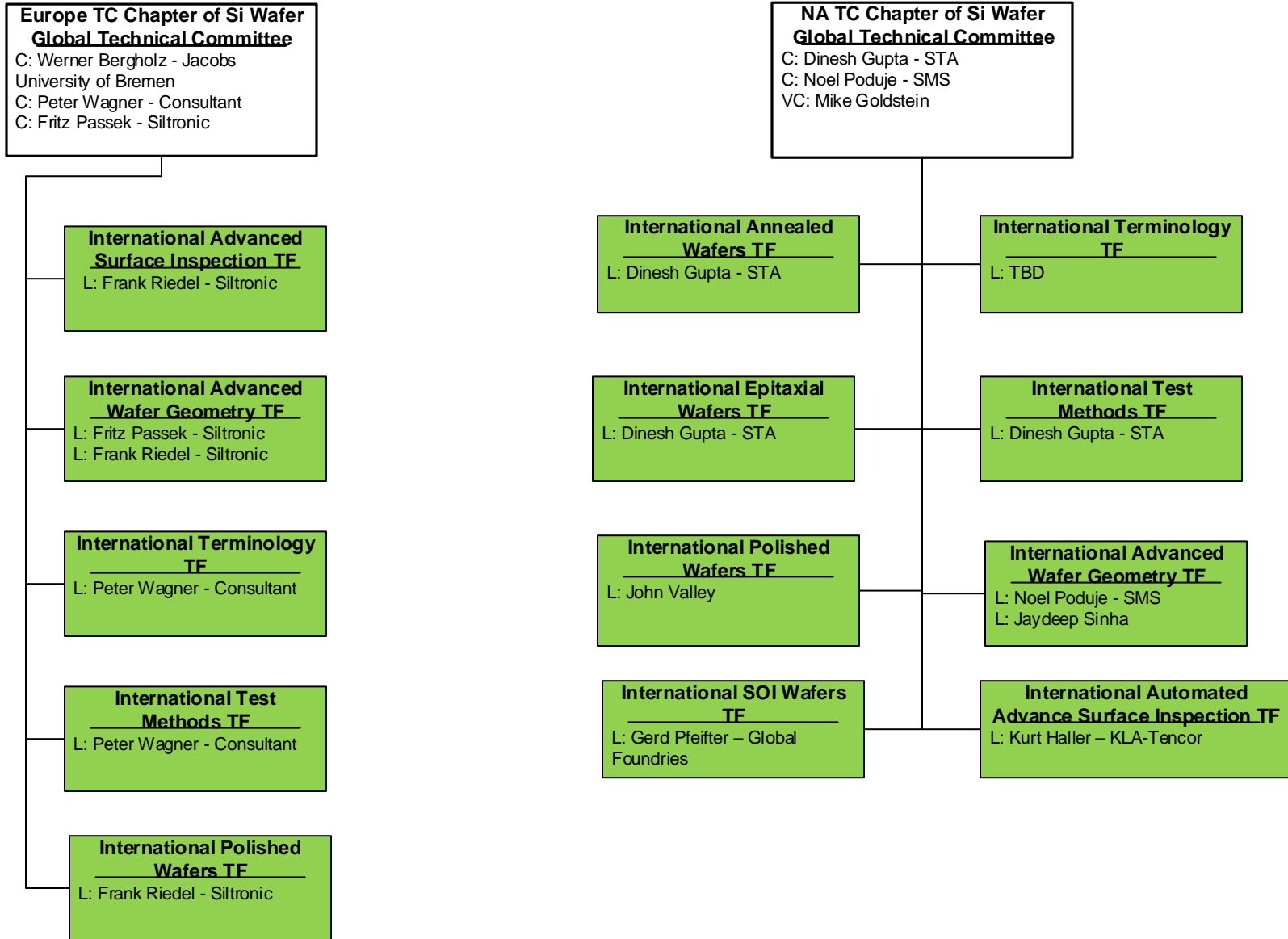
PV Materials Global Technical Committee



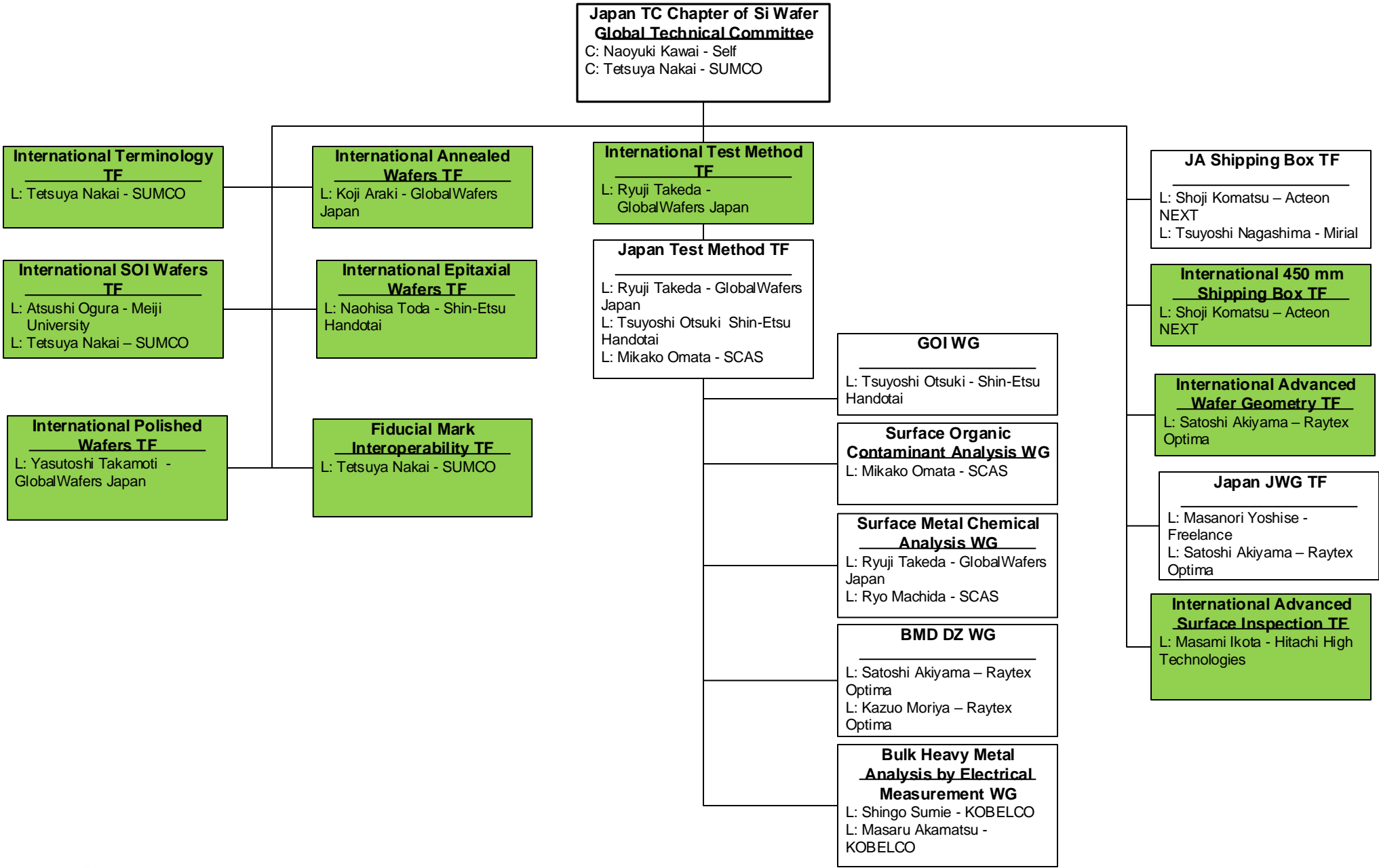
Physical Interfaces & Carriers Global Technical Committee



Silicon Wafer Global Technical Committee



Silicon Wafer Global Technical Committee



Traceability Global Technical Committee

